Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
1	IC1	1		HT45F0058	Holtek	Induction Cooker Flash MCU	16-pin NSOP		
2	IC2	1		PN8044	Chipown	Non-isolated PFM Converter	DIP-8		
3	IC3	1		L4931CZ50-AP	STMicroelectronics	LDO Voltage Regulator	TO-92-3		
4	Q1	1		GT20N135SRA	TOSHIBA	IGBT, 1350 V, 40 A	TO-247		
5	Q2, Q3	2		TBC847	TOSHIBA	NPN Transistor, 50 V, 0.15 A	SOT-23		
6	Q4	1		TBC857	TOSHIBA	PNP Transistor, -50 V, -0.15 A	SOT-23		
7	Q5	1		2SC6135	TOSHIBA	NPN Transistor, 50 V, 1 A	SOT-323F (UFM)		
8	D1, D3, D6, D7, D8, D9, D10, D12	8		US1M	DIODES	Rectifier Diode, 1000 V, 1 A		2.29 x 4.00	
9	D2	1		GBJ2010	DIODES	Bridge Diode, 1000 V, 20 A		Through Hole	
10	D4	1		KDZV5.1B	ROHM	Zenner Diode, 5.1 V, 1 W		1.50 x 2.50	
11	D5	1		CRZ18	TOSHIBA	Zenner Diode, 18 V, 0.7 W	S-FLAT	1.6 x 3.5	
12	D11	1		SMAZ5V1	DIODES	Zenner Diode, 5.1 V		2.29 x 4.00	
13	L1	1	300 µH	MGB16G30-81-P100Y	ueno	10 A, 139 mOhm			
14	C1	1	0.24 µF	1BH424D1200-10	BM cap	Metalized polypropylene film, 630 VAC, ±5 %		Through Hole	
15	C2, C3	2	5 µF	1BH550D400-15	BM cap	Metalized polypropylene film, 275 VAC, X2, ±5 %		Through Hole	
16	C4	1	0.1 µF	890324023023CS	Wurth	Metalized polypropylene film, 275 VAC, X2, ±10 %		Through Hole	
17	C5, C9, C14	3	1 µF			Ceramic, 50 V, ±10 %		2.0 x 1.25 (0805)	
18	C6, C10, C15	3	330 pF			Ceramic, 50 V, ±10 %		2.0 x 1.25 (0805)	
19	C7, C13, C17, C19, C21	5	0.1 µF			Ceramic, 50 V, ±10 %		2.0 x 1.25 (0805)	
20	C8	1	1000 pF	562R5GAD10	Vishay	Ceramic, 1 kV, ±20 %		Through Hole	
21	C11	1	240 pF			Ceramic, 50 V, ±10 %		2.0 x 1.25 (0805)	
22	C12	1	4.7 µF	EKMQ451ELL4R7MJC5S	NIPPON CHEMI-CON	Aluminum Electrolytic, 450 V, ±20 %		Through Hole	

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
23	C16	1	4.7 µF	EKYA500ELL4R7ME11D	NIPPON CHEMI-CON	Aluminum Electrolytic, 50 V, ±20 %		Through Hole	
24	C18	1	0.027 µF			Ceramic, 50 V, ±10 %		2.0 x 1.25 (0805)	
25	C20	1	220 pF			Ceramic, 50 V, ±10 %		2.0 x 1.25 (0805)	
26	C22	1	470 µF	EKYA350ELL471MJ16S	NIPPON CHEMI-CON	Aluminum Electrolytic, 35 V, ±20 %		Through Hole	
27	C23	1	220 µF	EKYA350ELL221MHB5D	NIPPON CHEMI-CON	Aluminum Electrolytic, 35 V, ±20 %		Through Hole	
28	C24, C25, C27	3	100 µF	EKYA350ELL101MF11D	NIPPON CHEMI-CON	Aluminum Electrolytic, 35 V, ±20 %		Through Hole	
29	C26	1	10 µF			Ceramic, 10 V, ±10 %		2.0 x 1.25 (0805)	
30	R1, R8, R26, R28, R33, R34, R35, R36	8	470 kΩ			±5 %, 250 mW		3.2 x 1.6 (1206)	
31	R2, R6, R9, R10, R15, R18, R22	7	110 kΩ			±5 %, 250 mW		3.2 x 1.6 (1206)	
32	R3, R4, R20, R23	4	68 Ω			±5 %, 250 mW		3.2 x 1.6 (1206)	
33	R5	1	150 kΩ			±5 %, 250 mW		3.2 x 1.6 (1206)	
34	R7	1	3.3 kΩ			±5 %, 250 mW		3.2 x 1.6 (1206)	
35	R11, R19, R44	3	10 kΩ			±5 %, 250 mW		3.2 x 1.6 (1206)	
36	R12	1	100 kΩ			±5 %, 250 mW		3.2 x 1.6 (1206)	
37	R13	1	0 Ω			2 A		3.2 x 1.6 (1206)	
38	R14	1	20 mΩ	MSR-5 R02 F	Arcol	Shunt ±1 %, 5 W		Through Hole	
39	R16	1	220 Ω			±5 %, 250 mW		3.2 x 1.6 (1206)	
40	R17	1	82 kΩ			±5 %, 250 mW		3.2 x 1.6 (1206)	
41	R21	1	75 kΩ			±5 %, 250 mW		3.2 x 1.6 (1206)	
42	R24	1	68 kΩ			±5 %, 250 mW		3.2 x 1.6 (1206)	
43	R25	1	10 kΩ			±1 %, 250 mW		3.2 x 1.6 (1206)	
44	R27	1	1.3 kΩ			±5 %, 250 mW		3.2 x 1.6 (1206)	
45	R29, R52	2	2 kΩ			±5 %, 250 mW		3.2 x 1.6 (1206)	
46	R31	1	5.1 kΩ			±1 %, 250 mW		3.2 x 1.6 (1206)	
47	R32	1	22 Ω	WS2M22R0J	Bourns	±20 %, 2 W		Through Hole	

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
48	R37	1	9.1 kΩ			±1 %, 250 mW		3.2 x 1.6 (1206)	
49	R38	1	47 kΩ			±5 %, 250 mW		3.2 x 1.6 (1206)	
50	R40	1	3.3 kΩ			±1 %, 250 mW		3.2 x 1.6 (1206)	
51	R41	1	4.3 kΩ			±1 %, 250 mW		3.2 x 1.6 (1206)	
52	R42	1	14 kΩ			±1 %, 250 mW		3.2 x 1.6 (1206)	
53	R43	1	20 kΩ			±5 %, 250 mW		3.2 x 1.6 (1206)	
54	R47	1	56 kΩ			±1 %, 250 mW		3.2 x 1.6 (1206)	
55	R50, R56	2	20 Ω			±5 %, 250 mW		3.2 x 1.6 (1206)	
56	R53, R54, R55	3	1 kΩ			±5 %, 250 mW		3.2 x 1.6 (1206)	
57	R62	1	390 Ω			±1 %, 250 mW		3.2 x 1.6 (1206)	
58	BZ1	1		PKM13EPYH4002-B0	Murata	Buzzer, 4 kHz		Through Hole	
59	F1	1		0034.3128.TR	SCHURTER	Fuse, 250 VAC, 12.5 A		Through Hole	
60	RTH1	1		NTHS1206N01N1003 KE	Vishay	Thermistor, 100k, B3964		3.2 x 1.6 (1206)	
61	RV1	1		MOV-14D561K	Bourns	Varistor, 560 V		Through Hole	
62	T1	1		S9369	SCITEC	CH Transformer		Through Hole	
63	CN1-1, CN1-2	2		4902	KEYSTONE	Connector		Through Hole	
64	CN2	1		B03B-XASK-1-A	JST	Connector		Through Hole	
65	CN3	1		T4B-SQ	JST	Header		Through Hole	
66	CN4	1		B04B-XASK-1-A	JST	Connector		Through Hole	
67	CN5	1		B02B-XASK-1-A	JST	Connector		Through Hole	
68	CN6	1		T3B-SQ	JST	Header		Through Hole	
69	JP1	1		T2B-SQ	JST	Header		Through Hole	
70	J3, J6, J7, J8	4				Jumper, l=20.0 mm		Through Hole	
71	J5, J9, J10, J11, J14	5				Jumper, l=15.0 mm		Through Hole	
72	J12, J13	2				Jumper, l=10.0 mm		Through Hole	
73	J15	1				Jumper, l=5.0 mm		Through Hole	
74	J16, J17, J18, J19, J20, J21, J22, J24,	12				Jumper, 2 A		3.2 x 1.6 (1206)	

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
	J25, J26, J27, J28								

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